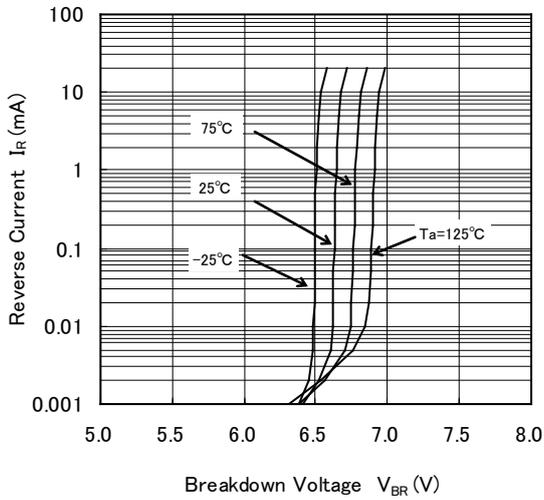
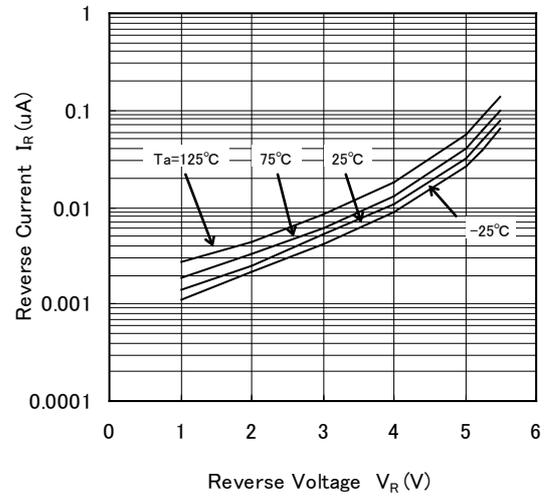


TYPICAL PERFORMANCE CHARACTERISTICS

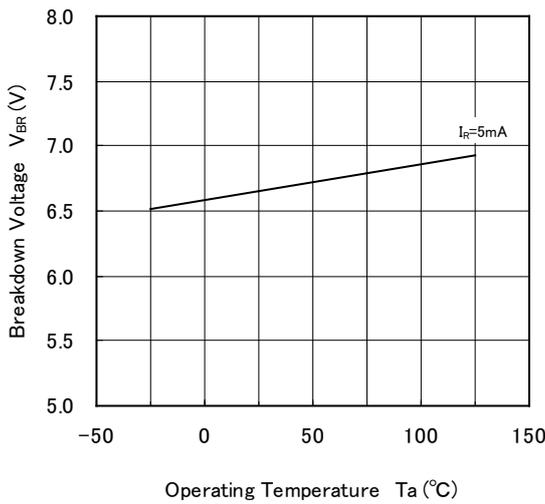
(1) Reverse Current vs. Breakdown Voltage



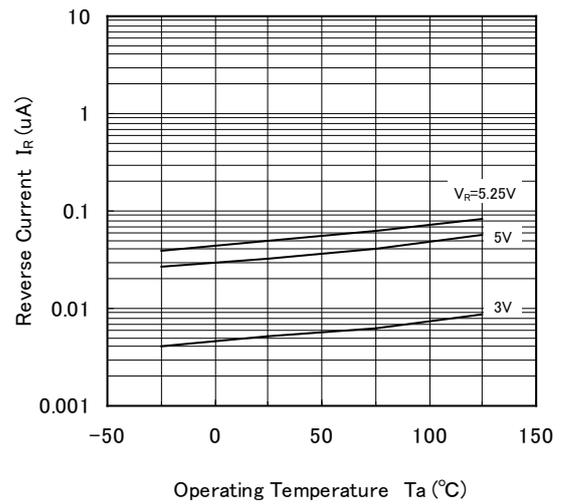
(2) Reverse Current vs. Reverse Voltage



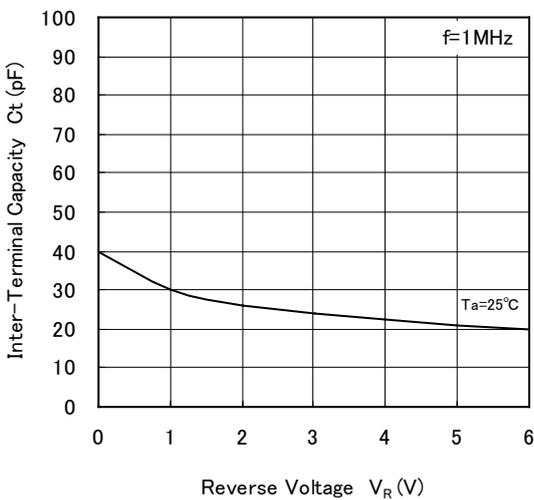
(3) Breakdown Voltage vs. Operating Temperature



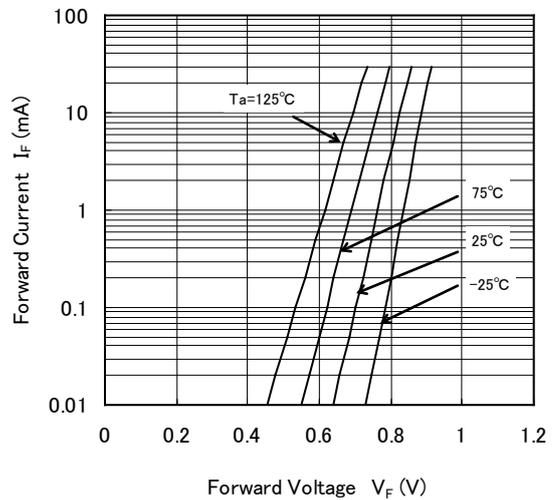
(4) Reverse Current vs. Operating Temperature



(5) Inter-Terminal Capacity vs. Reverse Voltage



(6) Forward Current vs. Forward Voltage



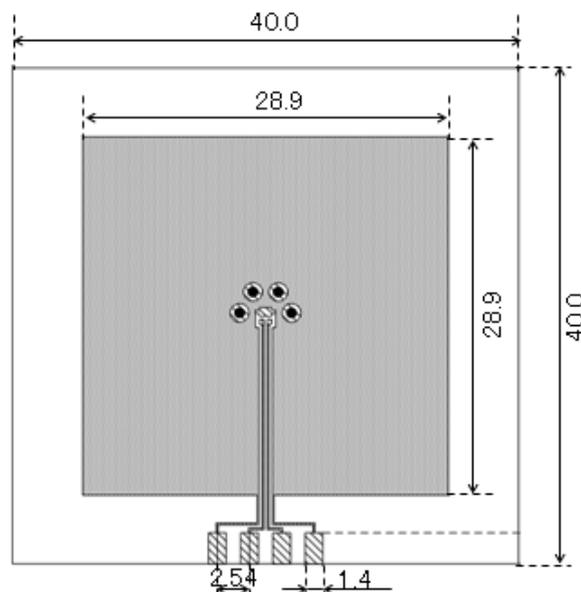
■ PACKAGING INFORMATION

● USP-3 Power Dissipation

Power dissipation data for the USP-3 is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board: Dimensions 40 x 40 mm (1600 mm² in one side)
Copper (Cu) traces occupy 50% of the board area in top and back faces.
Package heat-sink is tied to the copper traces.
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6 mm
- Through-hole: 4 x 0.8 Diameter

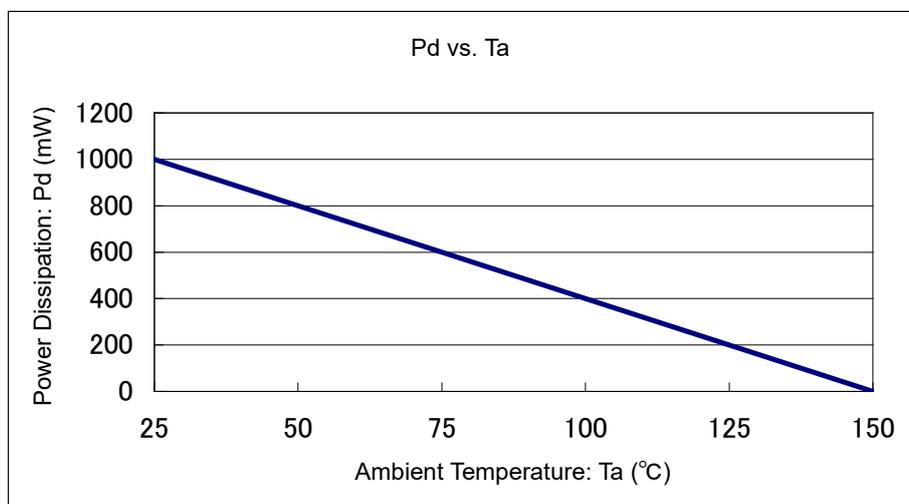


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (T_j max = 150°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1000	125.00
150	0	



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